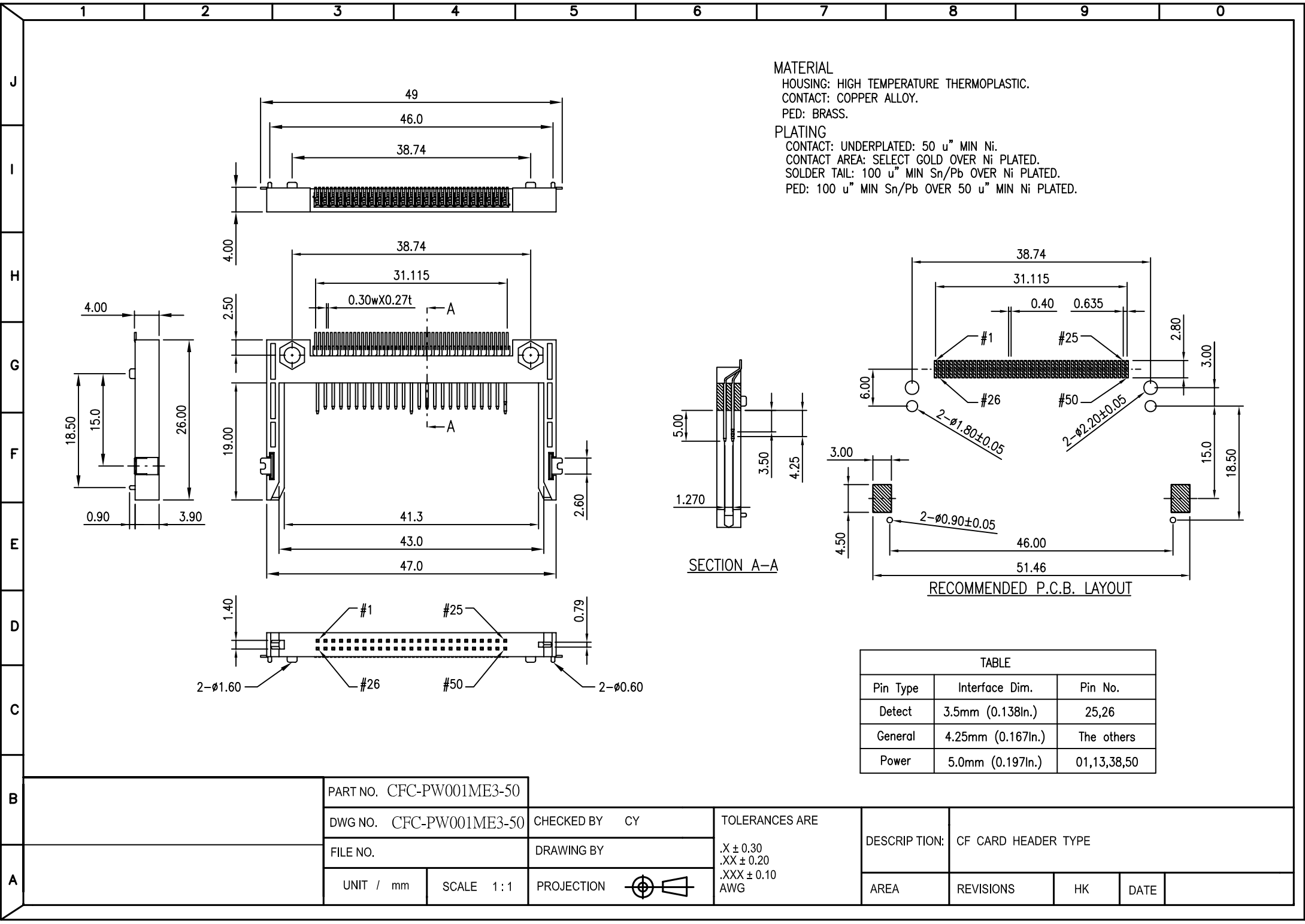




MATERIAL

HOUSING: HIGH TEMPERATURE THERMOPLASTIC.

CONTACT: COPPER ALLOY.

PED: BRASS.

PLATING

CONTACT: UNDERPLATED: 50 u" MIN Ni.

CONTACT AREA: SELECT GOLD OVER Ni PLATED.

SOLDER TAIL: 100 u" MIN Sn/Pb OVER Ni PLATED.

PED: 100 u" MIN Sn/Pb OVER 50 u" MIN Ni PLATED.

SECTION A-A

RECOMMENDED P.C.B. LAYOUT

TABLE

Pin Type	Interface Dim.	Pin No.
Detect	3.5mm (0.138In.)	25,26
General	4.25mm (0.167In.)	The others
Power	5.0mm (0.197In.)	01,13,38,50

PART NO. CFC-PW001ME3-50

DWG NO. CFC-PW001ME3-50

CHECKED BY CY

TOLERANCES ARE

FILE NO.

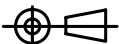
DRAWING BY

.X ± 0.30
.XX ± 0.20
.XXX ± 0.10
AWG

UNIT / mm

SCALE 1:1

PROJECTION



DESCRIPTION:

CF CARD HEADER TYPE

AREA

REVISIONS

HK

DATE